EPO-TEK® ED1021

Epoxy; Epoxide

Epoxy Technology Inc.

Message:

A single component, silver-filled epoxy designed for low power semiconductor LED die attach applications. Unique features include its ability to achieve high thermal conductivity values at low cure temperatures and a very shiny silver appearance which enhances overall LED brightness. Other benefits include long pot-life, low viscosity and high thixotropy making it ideal for wafer level stamping as well as syringe dispensing.

Formerly 77-190-2

General Information			
Filler / Reinforcement	Silver		
Features	Low Viscosity		
	Thermally Conductive		
	Thixotropic		
Uses	Adhesives		
	Electrical/Electronic Applications		
	LEDs		
Agency Ratings	EC 1907/2006 (REACH)		
	EU 2003/11/EC		
	EU 2006/122/EC		
RoHS Compliance	RoHS Compliant		
Forms	Paste		
Physical	Nominal Value	Unit	
Ion Type			
CI-	< 10	ppm	
K+	1	ppm	
Na+	3	ppm	
NH4+	9	ppm	
Particle Size	< 20.0	μm	
Degradation Temperature	403	°C	
Operating Temperature			
Continuous	-55 to 200	°C	
Intermittent	-55 to 300	°C	
Storage Modulus (23°C)	178	MPa	
Thixotropic Index	4.20		
Weight Loss on Heating			
200°C	0.35	%	
250°C	0.41	%	

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